

AMIS-30521, NCV70521

Micro-Stepping Motor Driver

Introduction

The AMIS-30521/NCV70521 is a micro-stepping stepper motor driver for bipolar stepper motors. The chip is connected through I/O pins and a SPI interface with an external microcontroller. The AMIS-30521/NCV70521 contains a current-translation table. It takes the next micro-step depending on the clock signal on the “NXT” input pin and the status of the “DIR” (= direction) register or input pin. The chip provides a so-called “Speed and Load Angle” output. This allows the creation of stall detection algorithms and control loops based on load-angle to adjust torque and speed. It is using a proprietary PWM algorithm for reliable current control.

The AMIS-30521/NCV70521 is implemented in I²T100 technology, enabling both high voltage analog circuitry and digital functionality on the same chip. The chip is fully compatible with the automotive voltage requirements.

The 521 is ideally suited for general purpose stepper motor applications in the automotive, industrial, medical and marine environment. The AMIS-30521 is intended for use in industrial applications. The NCV70521 version is qualified for use in automotive applications.

Features

- Dual H-Bridge for 2 Phase Stepper Motors
- Programmable Peak-Current Up to 1.2 A Continuous (1.5 A Short Time), Using a 5-Bit Current DAC
- On-Chip Current Translator
- SPI Interface
- Speed and Load-Angle Output
- 7 Step Modes from Full Step-up to 32 Micro-Steps
- Fully Integrated Current-Sense
- PWM Current Control with Automatic Selection of Fast and Slow Decay
- Low EMC PWM with Selectable Voltage Slopes
- Active Flyback Diodes
- Full Output Protection and Diagnosis
- Thermal Warning and Shutdown
- Digital IO's Compatible with 5 V and 3.3 V Microcontrollers
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes
- These are Pb-Free Devices*

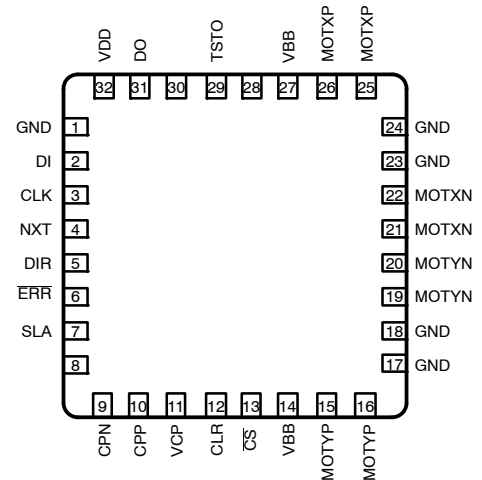
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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PINOUT



PC20070309.2

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 26 of this data sheet.

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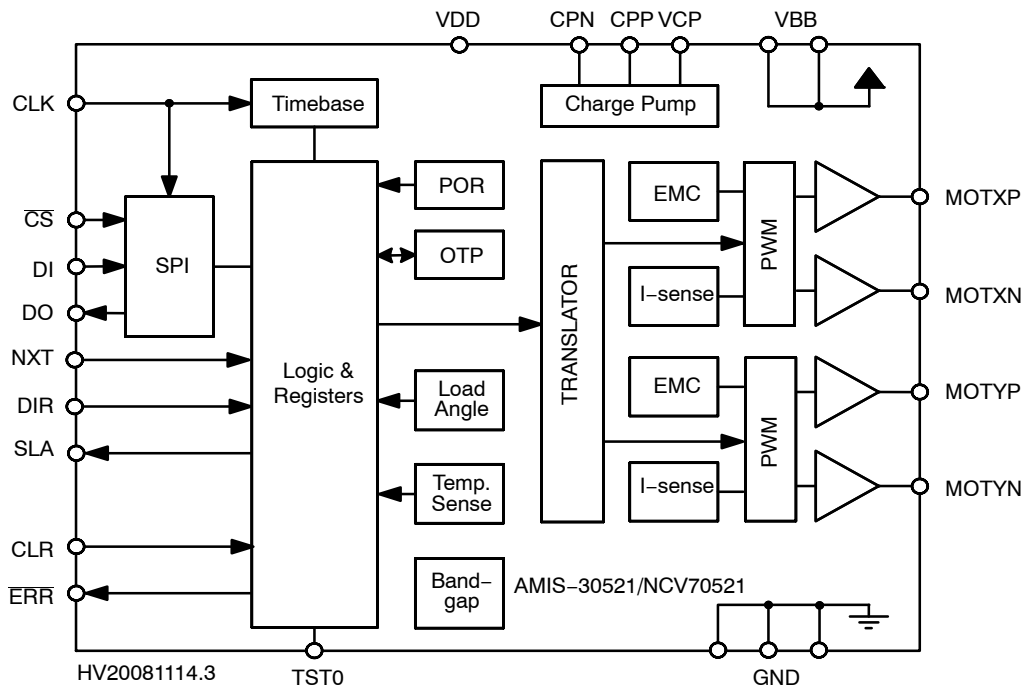


Figure 1. Block Diagram AMIS-30521/NCV70521

Table 1. PIN DESCRIPTION

| Name | Pin | Description | Type | Equivalent Schematic |
|-------|--------|---|----------------|----------------------|
| GND | 1 | Ground | Supply | |
| DI | 2 | SPI Data In | Digital Input | Type 2 |
| CLK | 3 | SPI Clock Input | Digital Input | Type 2 |
| NXT | 4 | Next Micro-Step Input | Digital Input | Type 2 |
| DIR | 5 | Direction Input | Digital Input | Type 2 |
| ERR | 6 | Error Output (Open Drain) | Digital Output | Type 4 |
| SLA | 7 | Speed Load Angle Output | Analog Output | Type 5 |
| / | 8 | No Function (to be Tied to Ground) | | |
| CPN | 9 | Negative Connection of Charge Pump Capacitor | High Voltage | |
| CPP | 10 | Positive Connection of Charge Pump Capacitor | High Voltage | |
| VCP | 11 | Charge-Pump Filter-Capacitor | High Voltage | |
| CLR | 12 | “Clear” = Chip Reset Input | Digital Input | Type 1 |
| CS | 13 | SPI Chip Select Input | Digital Input | Type 2 |
| VBB | 14 | High Voltage Supply Input | Supply | Type 3 |
| MOTYP | 15, 16 | Positive End of Phase Y Coil Output | Driver Output | |
| GND | 17, 18 | Ground | Supply | |
| MOTYN | 19, 20 | Negative End of Phase Y coil Output | Driver Output | |
| MOTXN | 21, 22 | Negative End of Phase X coil Output | Driver Output | |
| GND | 23, 24 | Ground | Supply | |
| MOTXP | 25, 26 | Positive End of Phase X Coil Output | Driver Output | |
| VBB | 27 | High Voltage Supply Input | Supply | Type 3 |
| / | 28 | No Function (Has to be Left Open in Normal Condition) | | |
| TSTO | 29 | Test pin input (to be Tied to Ground in Normal Operation) | Digital Input | |
| / | 30 | No Function (to be Tied to Ground) | | |
| DO | 31 | SPI Data Output (Open Drain) | Digital Output | Type 4 |
| VDD | 32 | Logic Supply Input (Needs External Decoupling Capacitor) | Supply | Type 3 |

Table 2. ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Min | Max | Unit |
|-----------|--|------|------|------|
| V_{BB} | Analog DC Supply Voltage (Note 1) | -0.3 | +40 | V |
| V_{DD} | Logic Supply Voltage | -0.3 | +7.0 | V |
| T_{ST} | Storage Temperature | -55 | +160 | °C |
| T_J | Junction Temperature (Note 2) | -50 | +175 | °C |
| V_{ESD} | Electrostatic Discharges on Component Level, All Pins (Note 3) | -2 | +2 | kV |
| V_{ESD} | Electrostatic Discharges on Component Level, HiV Pins (Note 4) | -8 | +8 | kV |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. For limited time < 0.5s
2. Circuit functionality not guaranteed.
3. Human Body Model (100 pF via 1.5 kΩ, according to JEDEC EIA-JESD22-A114-B)
4. HiV = High Voltage Pins MOTxx, V_{BB} , GND; Human Body Model (100 pF via 1.5 kΩ, according to JEDEC EIA-JESD22-A114-B)

Table 3. THERMAL RESISTANCE

| Package | Thermal Resistance | | | Unit |
|---------|-------------------------|---------------------|------------|------|
| | Junction-to-Exposed Pad | Junction-to-Ambient | | |
| | | 1S0P Board | 2S2P Board | |
| NQFP-32 | 0.95 | 60 | 30 | K/W |

EQUIVALENT SCHEMATICS

The following figure gives the equivalent schematics of the user relevant inputs and outputs. The diagrams are simplified representations of the circuits used.

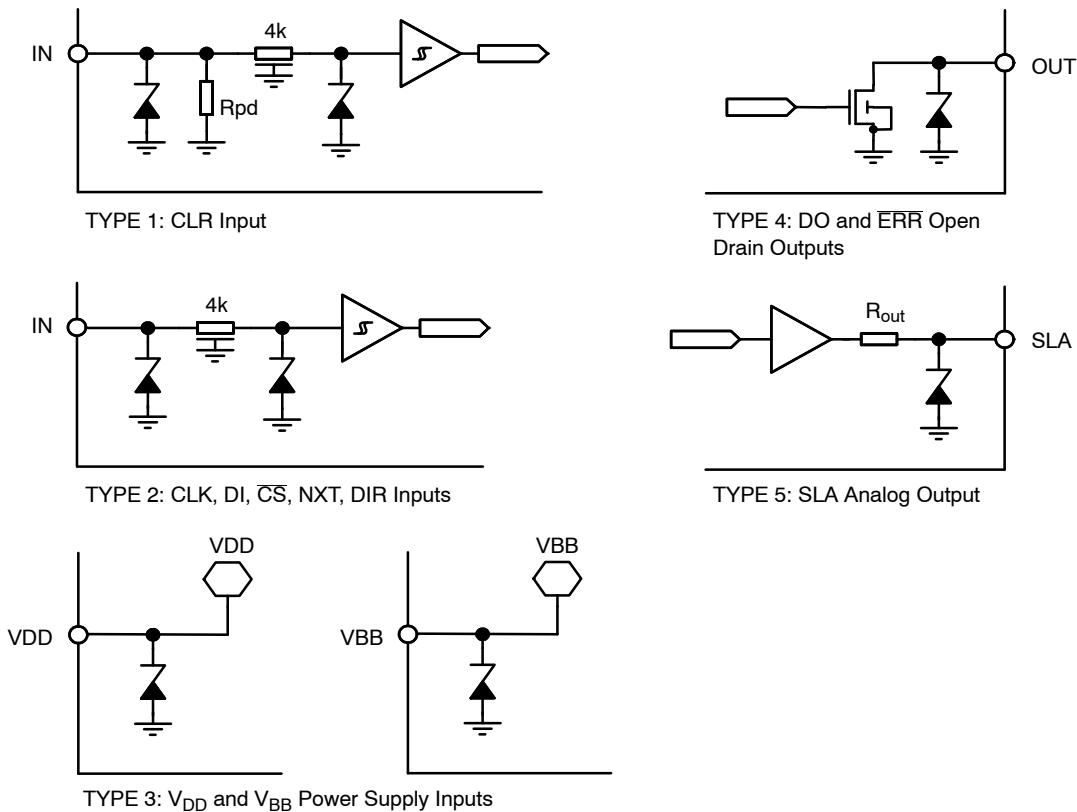


Figure 2. In- and Output Equivalent Diagrams

PACKAGE THERMAL CHARACTERISTICS

The AMIS-30521/NCV70521 is available in an NQFP-32 package. For cooling optimizations, the NQFP has an exposed thermal pad which has to be soldered to the PCB ground plane. The ground plane needs thermal vias to conduct the heat to the bottom layer. Figure 3 gives an example for good power distribution solutions.

For precise thermal cooling calculations the major thermal resistances of the device are given. The thermal media to which the power of the devices has to be given are:

- Static environmental air (via the case)
- PCB board copper area (via the exposed pad)

The thermal resistances are presented in Table 5: DC Parameters.

The major thermal resistances of the device are the R_{th} from the junction to the ambient (R_{thja}) and the overall R_{th} from the junction to exposed pad (R_{thjp}). In Table 3 one can find the values for the R_{thja} simulated according to JESD-51.

The R_{thja} for 2S2P is simulated conform JEDEC JESD-51 as follows:

- A 4-layer printed circuit board with inner power planes and outer (top and bottom) signal layers is used
- Board thickness is 1.46 mm (FR4 PCB material)
- The 2 signal layers: 70 μm thick copper with an area of 5500 mm^2 copper and 20% conductivity
- The 2 power internal planes: 36 μm thick copper with an area of 5500 mm^2 copper and 90% conductivity

The R_{thja} for 1S0P is simulated conform JEDEC JESD-51 as follows:

- A 1-layer printed circuit board with only 1 layer
- Board thickness is 1.46 mm (FR4 PCB material)
- The layer has a thickness of 70 μm copper with an area of 5500 mm^2 copper and 20% conductivity

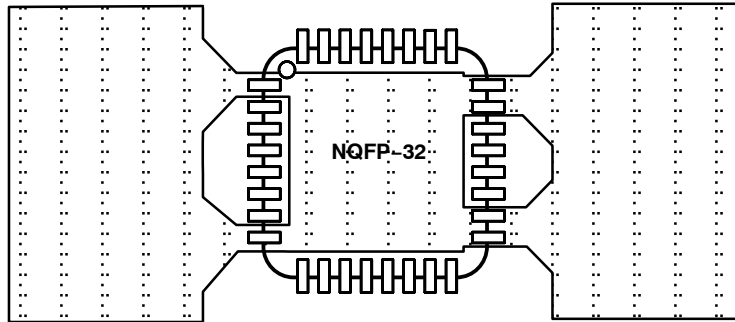


Figure 3. Example of NQFP-32 PCB Ground Plane Layout in Top View (Preferred Layout at Top and Bottom)

ELECTRICAL SPECIFICATION

Recommended Operation Conditions

Operating ranges define the limits for functional operation and parametric characteristics of the device. Note that the functionality of the chip outside these operating

ranges is not guaranteed. Operating outside the recommended operating ranges for extended periods of time may affect device reliability.

Table 4. OPERATING RANGES

| Symbol | Parameter | Min | Max | Unit |
|----------|----------------------|------|---------------|--------------------|
| V_{BB} | Analog DC supply | +6 | +30 | V |
| V_{DD} | Logic supply voltage | 4.75 | 5.25 | V |
| T_J | Junction temperature | -40 | +172 (Note 5) | $^{\circ}\text{C}$ |

5. No more than 100 cumulative hours in life time above T_{tw}

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Table 5. DC PARAMETERS

(DC Parameters are Given for V_{BB} and Temperature in Their Operating Ranges Unless Otherwise Specified)
 Convention: Currents Flowing in the Circuit are Defined as Positive

| Symbol | Pin(s) | Parameter | Remark/Test Conditions | Min | Typ | Max | Unit |
|--------|--------|-----------|------------------------|-----|-----|-----|------|
|--------|--------|-----------|------------------------|-----|-----|-----|------|

SUPPLY INPUTS

| | | | | | | | |
|-----------|----------|------------------------------------|------------------|------|-----|------|---------|
| V_{BB} | V_{BB} | Nominal Operating Supply Range | | 6 | | 30 | V |
| I_{BB} | | Total Current Consumption | Unloaded Outputs | | | 8 | mA |
| I_{BBS} | | Sleep Current in V_{BB} (Note 7) | Unloaded Outputs | | | 100 | μ A |
| V_{DD} | V_{DD} | Logic Supply Voltage | | 4.75 | 5 | 5.25 | V |
| I_{DDD} | | Dynamic Current (Note 6) | | | 7.5 | 10 | mA |
| I_{DDS} | | Sleep Current in V_{DD} (Note 7) | | | | 100 | μ A |

POWER ON RESET (POR) (Note 10)

| | | | | | | | |
|-------------|----------|--|-------------------------|------|------|------|---|
| V_{DDH} | V_{DD} | Internal POR Comparator Threshold | V _{DD} Rising | 3.85 | 4.20 | 4.55 | V |
| V_{DDL} | | Internal POR Comparator Threshold | V _{DD} Falling | | 3.85 | | V |
| V_{DDHYS} | | Hysteresis Between V_{DDH} and V_{DDL} | | 0.10 | 0.35 | 0.60 | V |

MOTOR DRIVER

| | | | | | | | | |
|------------------|--|---|--|-----|------|------|----------|----------|
| $I_{MDmax,Peak}$ | $MOTXP$ $MOTXN$ $MOTYP$ $MOTYN$ | Max Peak Current Through Motor Coil | T _J = -40°C | | 1600 | | mA | |
| I_{MDabs} | | Absolute Error on Coil Current | T _J = 125°C | -10 | | 10 | % | |
| I_{MDrel} | | Error On Current Ratio I_{coilx}/I_{coily} | | -7 | | 7 | % | |
| I_{SET_TC1} | | Temperature Coefficient of Coil Current Set-Level, CUR[4:0] = 0...27 | T _J ≤ 160°C | | | -240 | ppm/K | |
| I_{SET_TC2} | | Temperature Coefficient of Coil Current Set-Level, CUR[4:0] = 28...31 | T _J ≤ 160°C | | | -490 | ppm/K | |
| R_{HS} | | On-Resistance High-Side Driver, (Note 9) CUR[4:0] = 0...31 | V _{BB} = 12 V, T _J = 27°C | | | 0.45 | 0.56 | Ω |
| | | | V _{BB} = 12 V, T _J = 160°C | | | 0.94 | 1.25 | Ω |
| R_{LS3} | | On-Resistance Low-Side Driver, (Note 9) CUR[4:0] = 23...31 | V _{BB} = 12 V, T _J = 27°C | | | 0.45 | 0.56 | Ω |
| | | | V _{BB} = 12 V, T _J = 160°C | | | 0.94 | 1.25 | Ω |
| R_{LS2} | | On-Resistance Low-Side Driver, (Note 9) CUR[4:0] = 16...22 | V _{BB} = 12 V, T _J = 27°C | | | 0.90 | 1.2 | Ω |
| | | | V _{BB} = 12 V, T _J = 160°C | | | 1.9 | 2.5 | Ω |
| R_{LS1} | | On-Resistance Low-Side Driver, (Note 9) CUR[4:0] = 9...15 | V _{BB} = 12 V, T _J = 27°C | | | 1.8 | 2.3 | Ω |
| | | | V _{BB} = 12 V, T _J = 160°C | | | 3.8 | 5.0 | Ω |
| R_{LS0} | | On-Resistance Low-Side Driver, (Note 9) CUR[4:0] = 0...8 | V _{BB} = 12 V, T _J = 27°C | | | 3.6 | 4.5 | Ω |
| | V _{BB} = 12 V, T _J = 160°C | | | | 7.5 | 10 | Ω | |
| I_{Mpd} | Pulldown Current | HiZ Mode | | | 1 | mA | | |

DIGITAL INPUTS

| | | | | | | | |
|---------------|--------------------------------|----------------------------|------------------------|------|--|-----------------|------------|
| I_{leak} | DI, CLK NXT, DIR CLR, CS | Input Leakage (Note 8) | T _J = 160°C | | | 0.5 | μ A |
| V_{IL} | | Logic Low Threshold | | 0 | | 0.75 | V |
| V_{IH} | | Logic High Threshold | | 2.20 | | V _{DD} | V |
| R_{pd_CLR} | CLR | Internal Pulldown Resistor | | 120 | | 280 | k Ω |
| R_{pd_TST} | TST0 | Internal Pulldown Resistor | | 3 | | 8 | k Ω |

6. Current with oscillator running, all analogue cells active, SPI communication and NXT pulses applied. No floating inputs. Guaranteed by design.
7. Current with all analogue cells in power down. Logic is powered but no clocks running. All outputs unloaded, no inputs floating.
8. Not valid for pins with internal Pulldown resistor
9. Characterization Data Only
10. POR is derived from V_{DD}. For proper POR operation V_{BB} needs to be minimal V_{BB_min}.

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Table 5. DC PARAMETERS

(DC Parameters are Given for V_{BB} and Temperature in Their Operating Ranges Unless Otherwise Specified)
 Convention: Currents Flowing in the Circuit are Defined as Positive

| Symbol | Pin(s) | Parameter | Remark/Test Conditions | Min | Typ | Max | Unit |
|--------|--------|-----------|------------------------|-----|-----|-----|------|
|--------|--------|-----------|------------------------|-----|-----|-----|------|

DIGITAL OUTPUTS

| | | | | | | | |
|----------|---------|----------------------------|-------------------------|--|--|------|---|
| V_{OL} | DO, ERR | Logic Low Level Open Drain | $I_{OL} = 5 \text{ mA}$ | | | 0.30 | V |
|----------|---------|----------------------------|-------------------------|--|--|------|---|

THERMAL WARNING AND SHUTDOWN

| | | | | | | | |
|-----------------------------|--|------------------|--|-----|---------------|-----|----|
| T_{tw} | | Thermal Warning | | 138 | 145 | 152 | °C |
| T_{tsd} (Notes 11, 12) | | Thermal Shutdown | | | $T_{tw} + 20$ | | °C |

CHARGE PUMP

| | | | | | | | |
|--------------|---------|---------------------------|---|---------------|--------------------|---------------|----|
| V_{cp} | VCP | Output Voltage | $6 \text{ V} \leq V_{BB} \leq 14 \text{ V}$ | | $2 * V_{BB} - 2.5$ | | V |
| | | | $14 \text{ V} < V_{BB} \leq 30 \text{ V}$ | $V_{BB} + 10$ | | $V_{BB} + 15$ | |
| C_{buffer} | | External Buffer Capacitor | | 180 | 220 | 470 | nF |
| C_{pump} | CPP CPN | External Pump Capacitor | | 180 | 220 | 470 | nF |

PACKAGE THERMAL RESISTANCE VALUES

| | | | | | | | |
|------------|------|--|---|--|------|--|-----|
| R_{thja} | NQFP | Thermal Resistance Junction-to-Ambient | Simulated Conform JEDEC JESD-51, (2S2P) | | 30 | | K/W |
| R_{thjp} | | Thermal Resistance Junction-to-Exposed Pad | | | 0.95 | | K/W |

SPEED AND LOAD ANGLE OUTPUT

| | | | | | | | |
|------------|--------------------------|---|----------|-----|------|----------------|----|
| V_{out} | SLA | Output Voltage Range | | 0.2 | | $V_{DD} - 0.2$ | V |
| V_{off} | | Output Offset SLA Pin | SLAG = 0 | -50 | | 50 | mV |
| | | SLAG = 1 | -30 | | 30 | mV | |
| G_{sla} | | Gain of SLA Pin = V_{BEMF} / V_{COIL} | SLAG = 0 | | 0.5 | | |
| | | SLAG = 1 | | | 0.25 | | |
| R_{out} | | Output Resistance SLA Pin | | | 0.23 | 1 | kΩ |
| C_{load} | Load Capacitance SLA Pin | | | | 50 | pF | |

11. No more than 100 cumulative hours in life time above T_{tw}
 12. Thermal shutdown is derived from Thermal Warning

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Table 6. AC PARAMETERS (AC Parameters are Given for V_{BB} and Temperature in Their Operating Ranges)

| Symbol | Pin(s) | Parameter | Remark/Test Conditions | Min | Typ | Max | Unit |
|----------------------------|--------|----------------------------------|------------------------|-----|-----|-----|------|
| INTERNAL OSCILLATOR | | | | | | | |
| f_{osc} | | Frequency of Internal Oscillator | | 3.6 | 4 | 4.4 | MHz |

MOTORDRIVER

| | | | | | | | |
|-------------|-------|--|---|------|------|------|-------------|
| f_{PWM} | MOTxx | PWM Frequency | Frequency Depends Only on Internal Oscillator | 20.8 | 22.8 | 24.8 | kHz |
| | | Double PWM Frequency | | 41.6 | 45.6 | 49.6 | kHz |
| f_d | | PWM Jitter Depth (Note 13) | | | 10 | | % f_{PWM} |
| T_{brise} | MOTxx | Turn-On Voltage Slope, 10% to 90% (Note 13) | EMC[1:0] = 00 | | 150 | | V/ μ s |
| | | | EMC[1:0] = 01 | | 100 | | V/ μ s |
| | | | EMC[1:0] = 10 | | 50 | | V/ μ s |
| | | | EMC[1:0] = 11 | | 25 | | V/ μ s |
| T_{bfall} | MOTxx | Turn-off Voltage Slope, 90% to 10% (Note 13) | EMC[1:0] = 00 | | 150 | | V/ μ s |
| | | | EMC[1:0] = 01 | | 100 | | V/ μ s |
| | | | EMC[1:0] = 10 | | 50 | | V/ μ s |
| | | | EMC[1:0] = 11 | | 25 | | V/ μ s |

DIGITAL OUTPUTS

| | | | | | | | |
|-----------|--------|---|--|--|--|----|----|
| T_{H2L} | DO ERR | Output Falltime from V_{inH} to V_{inL} | Capacitive Load 400 pF and Pullup Resistor of 1.5 k Ω | | | 50 | ns |
|-----------|--------|---|--|--|--|----|----|

CHARGE PUMP

| | | | | | | | |
|-----------|---------|---------------------------------------|--------------------------|--|-----|---|-----|
| f_{CP} | CPN CPP | Charge Pump Frequency | | | 250 | | kHz |
| T_{CPU} | MOTxx | Startup Time of Charge Pump (Note 14) | Spec External Components | | | 5 | ms |

CLR FUNCTION

| | | | | | | | |
|-----------|-----|-----------------------------|--|-----|--|--|---------|
| t_{CLR} | CLR | Minimum Time for Hard Reset | | 100 | | | μ s |
|-----------|-----|-----------------------------|--|-----|--|--|---------|

NXT FUNCTION

| | | | | | | | |
|-----------------|-----|--|--------------|-----|-----|--|---------|
| t_{NXT_HI} | NXT | NXT Minimum, High Pulse Width | See Figure 4 | 2.0 | | | μ s |
| t_{NXT_LO} | | NXT Minimum, Low Pulse Width | See Figure 4 | 2.0 | | | μ s |
| t_{DIR_SET} | | NXT Hold Time, Following Change of DIR | See Figure 4 | | 2.0 | | μ s |
| t_{DIR_HOLD} | | NXT Hold Time, Before Change of DIR | See Figure 4 | | 2.0 | | μ s |

13. Characterization Data Only
 14. Guaranteed by design.

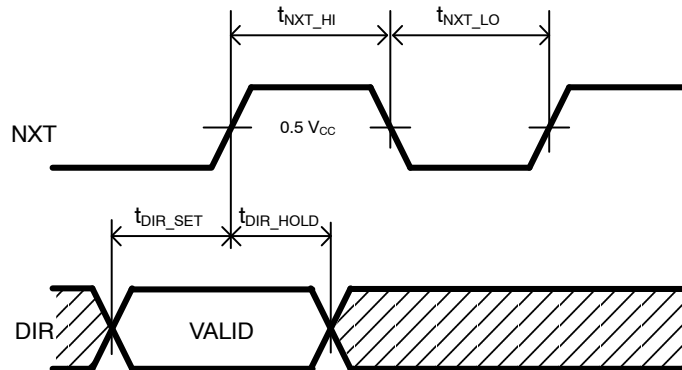


Figure 4. NXT-Input Timing Diagram

Table 7. SPI TIMING PARAMETERS

| Symbol | Parameter | Min | Typ | Max | Unit |
|-----------------|---|-----|-----|-----|---------|
| t_{CLK} | SPI Clock Period | 1 | | | μs |
| t_{CLK_HIGH} | SPI Clock High Time | 100 | | | ns |
| t_{CLK_LOW} | SPI Clock Low Time | 100 | | | ns |
| t_{SET_DI} | DI Setup Time, Valid Data Before Rising Edge of CLK | 50 | | | ns |
| t_{HOLD_DI} | DI Hold Time, Hold Data After Rising Edge of CLK | 50 | | | ns |
| t_{CSB_HIGH} | \overline{CS} High Time | 2.5 | | | μs |
| t_{SET_CSB} | \overline{CS} Setup Time, \overline{CS} Low Before Rising Edge of CLK | 100 | | | ns |
| t_{SET_CLK} | CLK Setup Time, CLK High Before Rising Edge of \overline{CS} | 100 | | | ns |

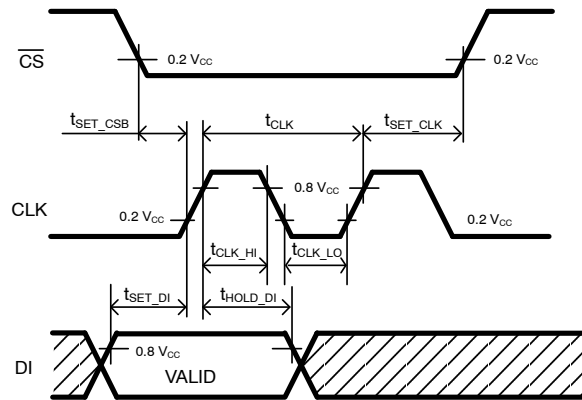


Figure 5. SPI Timing

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TYPICAL APPLICATION SCHEMATIC

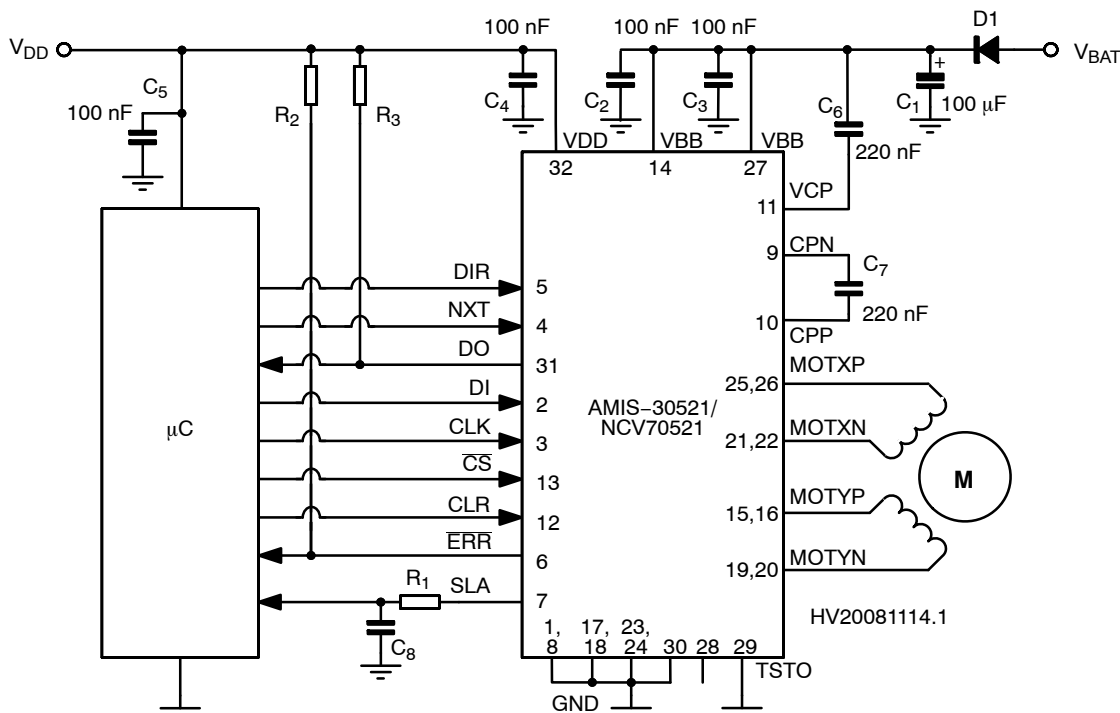


Figure 6. Typical Application Schematic AMIS-30521/NCV70521

Table 8. EXTERNAL COMPONENTS LIST AND DESCRIPTION

| Component | Function | Typ. Value | Tolerance | Unit |
|---------------------------------|--|------------|-----------|------|
| C ₁ | V _{BB} Buffer Capacitor (Low ESR < 1 Ω) | 100 | -20 +80% | µF |
| C ₂ , C ₃ | V _{BB} Decoupling Block Capacitor | 100 | -20 +80% | nF |
| C ₄ | V _{DD} Buffer Capacitor | 220 | ± 20% | nF |
| C ₅ | V _{DD} Buffer Capacitor | 100 | ± 20% | nF |
| C ₆ | Charge-Pump Buffer Capacitor | 220 | ± 20% | nF |
| C ₇ | Charge-Pump Pumping Capacitor | 220 | ± 20% | nF |
| C ₈ | Low Pass Filter SLA | 1 | ± 20% | nF |
| R ₁ | Low Pass Filter SLA | 5.6 | ± 1% | kΩ |
| R ₂ , R ₃ | Pullup Resistor Open Drain Output | 4.7 | ± 1% | kΩ |
| D ₁ | Reverse Protection Diode | MURD530 | | |

FUNCTIONAL DESCRIPTION

H-Bridge Drivers

A full H-bridge is integrated for each of the two stator windings. Each H-bridge consists of two low-side and two high-side N-type MOSFET switches. Writing logic '0' in bit <MOTEN> disables all drivers (High-Impedance). Writing logic '1' in this bit enables both bridges and current can flow in the motor stator windings.

In order to avoid large currents through the H-bridge switches, it is guaranteed that the top- and bottom switches of the same half-bridge are never conductive simultaneously (interlock delay).

A two-stage protection against shorts on motor lines is implemented. In a first stage, the current in the driver is

limited. Secondly, when excessive voltage is sensed across the transistor, the transistor is switched-off.

In order to reduce the radiated/conducted emission, voltage slope control is implemented in the output switches. The output slope is defined by the gate-drain capacitance of output transistor and the (limited) current that drives the gate. There are two trimming bits for slope control (See Table 12 SPI Control Parameter Overview EMC[1:0]).

The power transistors are equipped with so-called "active diodes": when a current is forced through the transistor switch in the reverse direction, i.e. from source to drain, then the transistor is switched on. This ensures that most of the current flows through the channel of the transistor instead of

through the inherent parasitic drain-bulk diode of the transistor.

Depending on the desired current range and the micro-step position at hand, the $R_{DS(on)}$ of the low-side transistors will be adapted such that excellent current-sense accuracy is maintained. The $R_{DS(on)}$ of the high-side transistors remain unchanged, see also the DC-parameter table for more details.

PWM Current Control

A PWM comparator compares continuously the actual winding current with the requested current and feeds back the information to a digital regulation loop. This loop then generates a PWM signal, which turns on/off the H-bridge switches. The switching points of the PWM duty-cycle are synchronized to the on-chip PWM clock.

The frequency of the PWM controller can be doubled to reduce the over-all current-ripple with a factor of two.

To further reduce the emission, an artificial jitter can be added to the PWM frequency. (see Table 12, SPI Control Register 1). The PWM frequency will not vary with changes in the supply voltage. Also variations in motor-speed or load-conditions of the motor have no effect. There are no external components required to adjust the PWM frequency.

Automatic Forward & Slow-Fast Decay

The PWM generation is in steady-state using a combination of forward and slow-decay. The absence of fast-decay in this mode, guarantees the lowest possible current-ripple “by design”. For transients to lower current levels, fast-decay is automatically activated to allow high-speed response. The selection of fast or slow decay is completely transparent for the user and no additional parameters are required for operation.

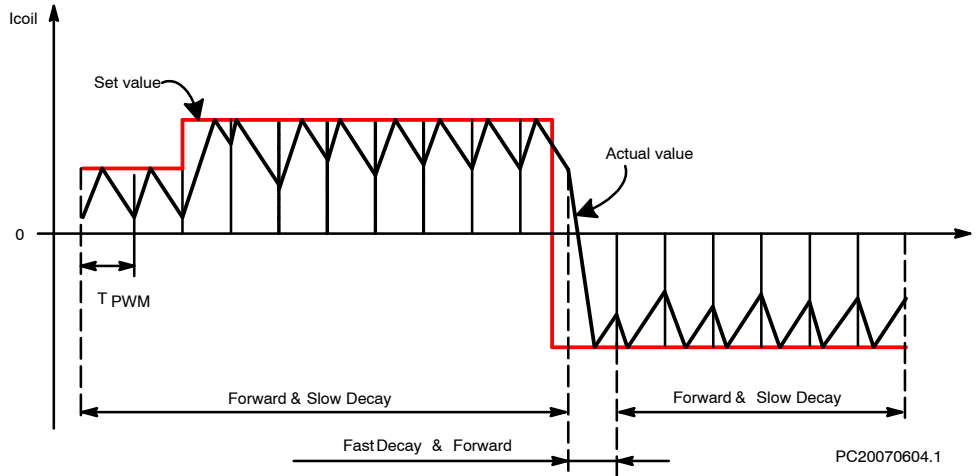


Figure 7. Forward & Slow/Fast Decay PWM

Automatic Duty Cycle Adaptation

In case the supply voltage is lower than $2 \cdot B_{emf}$, then the duty cycle of the PWM is adapted automatically to $>50\%$ to

maintain the requested average current in the coils. This process is completely automatic and requires no additional parameters for operation.

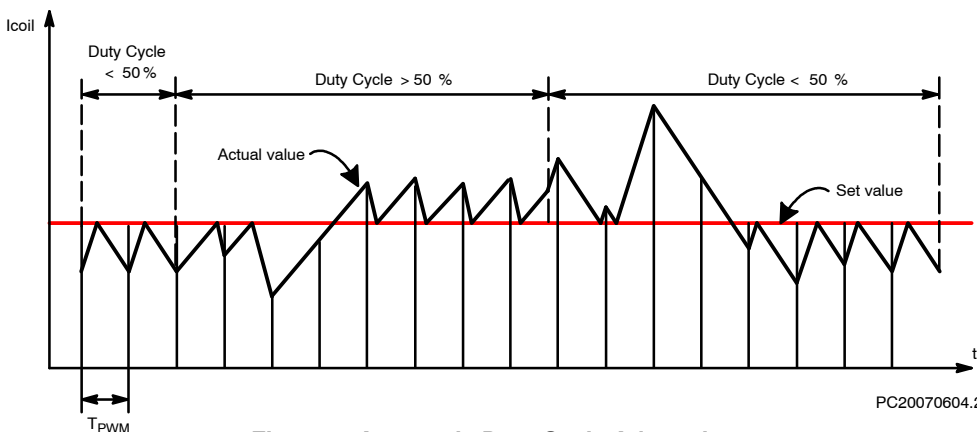


Figure 8. Automatic Duty Cycle Adaptation

Step Translator and Step Mode

The Step Translator provides the control of the motor by means of SPI register Stepmode: SM[2:0], SPI register DIRCNTRL, and input pins DIR and NXT. It is translating consecutive steps in corresponding currents in both motor coils for a given stepmode.

One out of 7 possible stepping modes can be selected through SPI-bits SM[2:0] (Table 12).

After power-on or hard reset, the coil-current translator is set to the default 1/32 micro-stepping at position '0'. Upon changing the Step Mode, the translator jumps to position 0* of the corresponding stepping mode. When

remaining in the same Step Mode, subsequent translator positions are all in the same column and increased or decreased with 1. Table 10 lists the output current vs. the translator position.

As shown in Figure 9 the output current-pairs can be projected approximately on a circle in the (I_x,I_y) plane. There are however two exceptions: uncompensated half step and full step. In these stepmodes the two currents are not regulated to a fraction of I_{max} but are in all intermediate steps regulated at 100%. In the (I_x,I_y) plane the current-pairs are projected on a square. Table 9 list the output current vs. the translator position for these cases.

Table 9. SQUARE TRANSLATOR TABLE FOR FULL STEP AND UNCOMPENSATED HALF STEP

| MSP[6:0] | Stepmode (SM[2:0]) | | % of I _{max} | |
|----------|-------------------------|-----------|-----------------------|--------|
| | 101 | 110 | Coil x | Coil y |
| | Uncompensated Half-Step | Full-Step | | |
| 000 0000 | 0* | – | 0 | 100 |
| 001 0000 | 1 | 1 | 100 | 100 |
| 010 0000 | 2 | – | 100 | 0 |
| 011 0000 | 3 | 2 | 100 | –100 |
| 100 0000 | 4 | – | 0 | –100 |
| 101 0000 | 5 | 3 | –100 | –100 |
| 110 0000 | 6 | – | –100 | 0 |
| 111 0000 | 7 | 0 | –100 | 100 |

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Table 10. CIRCULAR TRANSLATOR TABLE

| MSP[6:0] | Stepmode (SM[2:0]) | | | | | % of I _{max} | |
|----------|--------------------|------|-----|-----|-----|-----------------------|--------|
| | 000 | 001 | 010 | 011 | 100 | Coil x | Coil y |
| | 1/32 | 1/16 | 1/8 | 1/4 | 1/2 | | |
| 000 0000 | 0 | 0* | 0* | 0* | 0* | 0 | 100 |
| 000 0001 | 1 | - | - | - | - | 3.5 | 98.8 |
| 000 0010 | 2 | 1 | - | - | - | 8.1 | 97.7 |
| 000 0011 | 3 | - | - | - | - | 12.7 | 96.5 |
| 000 0100 | 4 | 2 | 1 | - | - | 17.4 | 95.3 |
| 000 0101 | 5 | - | - | - | - | 22.1 | 94.1 |
| 000 0110 | 6 | 3 | - | - | - | 26.7 | 93 |
| 000 0111 | 7 | - | - | - | - | 31.4 | 91.8 |
| 000 1000 | 8 | 4 | 2 | 1 | - | 34.9 | 89.5 |
| 000 1001 | 9 | - | - | - | - | 38.3 | 87.2 |
| 000 1010 | 10 | 5 | - | - | - | 43 | 84.9 |
| 000 1011 | 11 | - | - | - | - | 46.5 | 82.6 |
| 000 1100 | 12 | 6 | 3 | - | - | 50 | 79 |
| 000 1101 | 13 | - | - | - | - | 54.6 | 75.5 |
| 000 1110 | 14 | 7 | - | - | - | 58.1 | 72.1 |
| 000 1111 | 15 | - | - | - | - | 61.6 | 68.6 |
| 001 0000 | 16 | 8 | 4 | 2 | 1 | 65.1 | 65.1 |
| 001 0001 | 17 | - | - | - | - | 68.6 | 61.6 |
| 001 0010 | 18 | 9 | - | - | - | 72.1 | 58.1 |
| 001 0011 | 19 | - | - | - | - | 75.5 | 54.6 |
| 001 0100 | 20 | 10 | 5 | - | - | 79 | 50 |
| 001 0101 | 21 | - | - | - | - | 82.6 | 46.5 |
| 001 0110 | 22 | 11 | - | - | - | 84.9 | 43 |
| 001 0111 | 23 | - | - | - | - | 87.2 | 38.3 |
| 001 1000 | 24 | 12 | 6 | 3 | - | 89.5 | 34.9 |
| 001 1001 | 25 | - | - | - | - | 91.8 | 31.4 |
| 001 1010 | 26 | 13 | - | - | - | 93 | 26.7 |
| 001 1011 | 27 | - | - | - | - | 94.1 | 22.1 |
| 001 1100 | 28 | 14 | 7 | - | - | 95.3 | 17.4 |
| 001 1101 | 29 | - | - | - | - | 96.5 | 12.7 |
| 001 1110 | 30 | 15 | - | - | - | 97.7 | 8.1 |
| 001 1111 | 31 | - | - | - | - | 98.8 | 3.5 |
| 010 0000 | 32 | 16 | 8 | 4 | 2 | 100 | 0 |
| 010 0001 | 33 | - | - | - | - | 98.8 | -3.5 |
| 010 0010 | 34 | 17 | - | - | - | 97.7 | -8.1 |
| 010 0011 | 35 | - | - | - | - | 96.5 | -12.7 |
| 010 0100 | 36 | 18 | 9 | - | - | 95.3 | -17.4 |
| 010 0101 | 37 | - | - | - | - | 94.1 | -22.1 |
| 010 0110 | 38 | 19 | - | - | - | 93 | -26.7 |
| 010 0111 | 39 | - | - | - | - | 91.8 | -31.4 |
| 010 1000 | 40 | 20 | 10 | 5 | - | 89.5 | -34.9 |
| 010 1001 | 41 | - | - | - | - | 87.2 | -38.3 |
| 010 1010 | 42 | 21 | - | - | - | 84.9 | -43 |
| 010 1011 | 43 | - | - | - | - | 82.6 | -46.5 |
| 010 1100 | 44 | 22 | 11 | - | - | 79 | -50 |
| 010 1101 | 45 | - | - | - | - | 75.5 | -54.6 |
| 010 1110 | 46 | 23 | - | - | - | 72.1 | -58.1 |
| 010 1111 | 47 | - | - | - | - | 68.6 | -61.6 |
| 011 0000 | 48 | 24 | 12 | 6 | 3 | 65.1 | -65.1 |
| 011 0001 | 49 | - | - | - | - | 61.6 | -68.6 |
| 011 0010 | 50 | 25 | - | - | - | 58.1 | -72.1 |
| 011 0011 | 51 | - | - | - | - | 54.6 | -75.5 |
| 011 0100 | 52 | 26 | 13 | - | - | 50 | -79 |
| 011 0101 | 53 | - | - | - | - | 46.5 | -82.6 |
| 011 0110 | 54 | 27 | - | - | - | 43 | -84.9 |
| 011 0111 | 55 | - | - | - | - | 38.3 | -87.2 |
| 011 1000 | 56 | 28 | 14 | 7 | - | 34.9 | -89.5 |
| 011 1001 | 57 | - | - | - | - | 31.4 | -91.8 |
| 011 1010 | 58 | 29 | - | - | - | 26.7 | -93 |
| 011 1011 | 59 | - | - | - | - | 22.1 | -94.1 |
| 011 1100 | 60 | 30 | 15 | - | - | 17.4 | -95.3 |
| 011 1101 | 61 | - | - | - | - | 12.7 | -96.5 |
| 011 1110 | 62 | 31 | - | - | - | 8.1 | -97.7 |

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Table 10. CIRCULAR TRANSLATOR TABLE

| MSP[6:0] | Stepmode (SM[2:0]) | | | | | % of I _{max} | |
|----------|--------------------|------|-----|-----|-----|-----------------------|--------|
| | 000 | 001 | 010 | 011 | 100 | Coil x | Coil y |
| | 1/32 | 1/16 | 1/8 | 1/4 | 1/2 | | |
| 011 1111 | 63 | - | - | - | - | 3.5 | -98.8 |
| 100 0000 | 64 | 32 | 16 | 8 | 4 | 0 | -100 |
| 100 0001 | 65 | - | - | - | - | -3.5 | -98.8 |
| 100 0010 | 66 | 33 | - | - | - | -8.1 | -97.7 |
| 100 0011 | 67 | - | - | - | - | -12.7 | -96.5 |
| 100 0100 | 68 | 34 | 17 | - | - | -17.4 | -95.3 |
| 100 0101 | 69 | - | - | - | - | -22.1 | -94.1 |
| 100 0110 | 70 | 35 | - | - | - | -26.7 | -93 |
| 100 0111 | 71 | - | - | - | - | -31.4 | -91.8 |
| 100 1000 | 72 | 36 | 18 | 9 | - | -34.9 | -89.5 |
| 100 1001 | 73 | - | - | - | - | -38.3 | -87.2 |
| 100 1010 | 74 | 37 | - | - | - | -43 | -84.9 |
| 100 1011 | 75 | - | - | - | - | -46.5 | -82.6 |
| 100 1100 | 76 | 38 | 19 | - | - | -50 | -79 |
| 100 1101 | 77 | - | - | - | - | -54.6 | -75.5 |
| 100 1110 | 78 | 39 | - | - | - | -58.1 | -72.1 |
| 100 1111 | 79 | - | - | - | - | -61.6 | -68.6 |
| 101 0000 | 80 | 40 | 20 | 10 | 5 | -65.1 | -65.1 |
| 101 0001 | 81 | - | - | - | - | -68.6 | -61.6 |
| 101 0010 | 82 | 41 | - | - | - | -72.1 | -58.1 |
| 101 0011 | 83 | - | - | - | - | -75.5 | -54.6 |
| 101 0100 | 84 | 42 | 21 | - | - | -79 | -50 |
| 101 0101 | 85 | - | - | - | - | -82.6 | -46.5 |
| 101 0110 | 86 | 43 | - | - | - | -84.9 | -43 |
| 101 0111 | 87 | - | - | - | - | -87.2 | -38.3 |
| 101 1000 | 88 | 44 | 22 | 11 | - | -89.5 | -34.9 |
| 101 1001 | 89 | - | - | - | - | -91.8 | -31.4 |
| 101 1010 | 90 | 45 | - | - | - | -93 | -26.7 |
| 101 1011 | 91 | - | - | - | - | -94.1 | -22.1 |
| 101 1100 | 92 | 46 | 23 | - | - | -95.3 | -17.4 |
| 101 1101 | 93 | - | - | - | - | -96.5 | -12.7 |
| 101 1110 | 94 | 47 | - | - | - | -97.7 | -8.1 |
| 101 1111 | 95 | - | - | - | - | -98.8 | -3.5 |
| 110 0000 | 96 | 48 | 24 | 12 | 6 | -100 | 0 |
| 110 0001 | 97 | - | - | - | - | -98.8 | 3.5 |
| 110 0010 | 98 | 49 | - | - | - | -97.7 | 8.1 |
| 110 0011 | 99 | - | - | - | - | -96.5 | 12.7 |
| 110 0100 | 100 | 50 | 25 | - | - | -95.3 | 17.4 |
| 110 0101 | 101 | - | - | - | - | -94.1 | 22.1 |
| 110 0110 | 102 | 51 | - | - | - | -93 | 26.7 |
| 110 0111 | 103 | - | - | - | - | -91.8 | 31.4 |
| 110 1000 | 104 | 52 | 26 | 13 | - | -89.5 | 34.9 |
| 110 1001 | 105 | - | - | - | - | -87.2 | 38.3 |
| 110 1010 | 106 | 53 | - | - | - | -84.9 | 43 |
| 110 1011 | 107 | - | - | - | - | -82.6 | 46.5 |
| 110 1100 | 108 | 54 | 27 | - | - | -79 | 50 |
| 110 1101 | 109 | - | - | - | - | -75.5 | 54.6 |
| 110 1110 | 110 | 55 | - | - | - | -72.1 | 58.1 |
| 110 1111 | 111 | - | - | - | - | -68.6 | 61.6 |
| 111 0000 | 112 | 56 | 28 | 14 | 7 | -65.1 | 65.1 |
| 111 0001 | 113 | - | - | - | - | -61.6 | 68.6 |
| 111 0010 | 114 | 57 | - | - | - | -58.1 | 72.1 |
| 111 0011 | 115 | - | - | - | - | -54.6 | 75.5 |
| 111 0100 | 116 | 58 | 29 | - | - | -50 | 79 |
| 111 0101 | 117 | - | - | - | - | -46.5 | 82.6 |
| 111 0110 | 118 | 59 | - | - | - | -43 | 84.9 |
| 111 0111 | 119 | - | - | - | - | -38.3 | 87.2 |
| 111 1000 | 120 | 60 | 30 | 15 | - | -34.9 | 89.5 |
| 111 1001 | 121 | - | - | - | - | -31.4 | 91.8 |
| 111 1010 | 122 | 61 | - | - | - | -26.7 | 93 |
| 111 1011 | 123 | - | - | - | - | -22.1 | 94.1 |
| 111 1100 | 124 | 62 | 31 | - | - | -17.4 | 95.3 |
| 111 1101 | 125 | - | - | - | - | -12.7 | 96.5 |
| 111 1110 | 126 | 63 | - | - | - | -8.1 | 97.7 |
| 111 1111 | 127 | - | - | - | - | -3.5 | 98.8 |

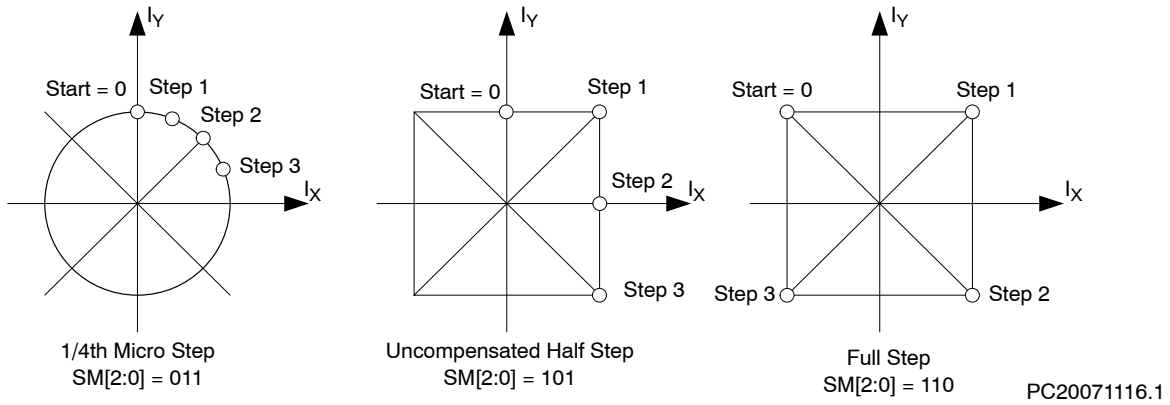


Figure 9. Translator Table: Circular and Square

Direction

The direction of rotation is selected by means of following combination of the DIR input pin and the SPI-controlled direction bit <DIRCTRL> as illustrated in Table 12.

NXT Input

Changes on the NXT input will move the motor current one step up/down in the translator table (even when the motor is disabled). Depending on the NXT-polarity bit <NXTP> (see Table 12), the next step is initiated either on the rising edge or the falling edge of the NXT input.

Translator Position

The translator position can be read in SPI Status Register 3. This is a 7-bit number equivalent to the 1/32th micro-step from Table 10: “Circular Translator Table” above. The translator position is updated immediately following a NXT trigger.

Synchronization of Step Mode and NXT Input

When step mode is re-programmed to another resolution, (Figure 11), this is put in effect immediately upon the first arriving “NXT” input. If the micro-stepping resolution is increased, the coil currents will be regulated to the nearest micro-step, according to the fixed grid of the increased resolution. If however the micro-stepping resolution is decreased, then it is possible to introduce an offset (or phase shift) in the micro-step translator table.

If the step resolution is decreased at a translator table position that is shared both by the old and new resolution setting, then the offset is zero and micro-stepping proceeds according to the translator table.

If the translator position is **not** shared both by the old and new resolution setting, then the micro-stepping proceeds with an offset relative to the translator table (See Figure 11 right hand side).

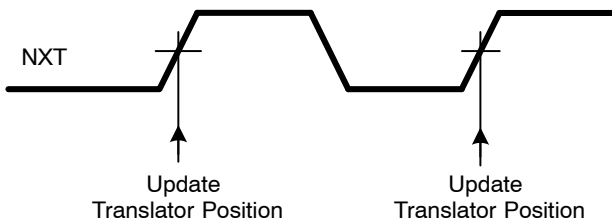


Figure 10. Translator Position Timing Diagram

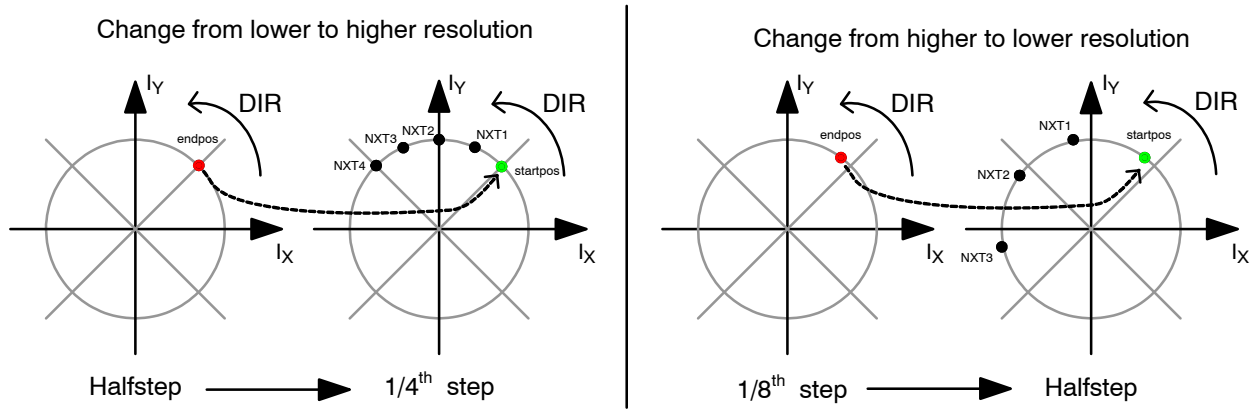


Figure 11. NXT-Step-Mode Synchronization

Left: change from lower to higher resolution. The left-hand side depicts the ending half-step position during which a new step mode resolution was programmed. The right-hand side diagram shows the effect of subsequent NXT commands on the micro-step position.

Right: change from higher to lower resolution. The left-hand side depicts the ending micro-step position during which a new step mode resolution was programmed. The right-hand side diagram shows the effect of subsequent NXT commands on the half-step position.

NOTE: It is advised to reduce the micro-stepping resolution only at micro-step positions that overlap with desired micro-step positions of the new resolution.

Programmable Peak-Current

The amplitude of the current waveform in the motor coils (coil peak current = I_{max}) is adjusted by means of an SPI parameter “CUR[4:0]” (Table 13). Whenever this

parameter is changed, the coil-currents will be updated immediately at the next PWM period. Figure 12 presents the Peak-Current and Current Ranges in conjunction to the Current setting (CUR[4:0]).

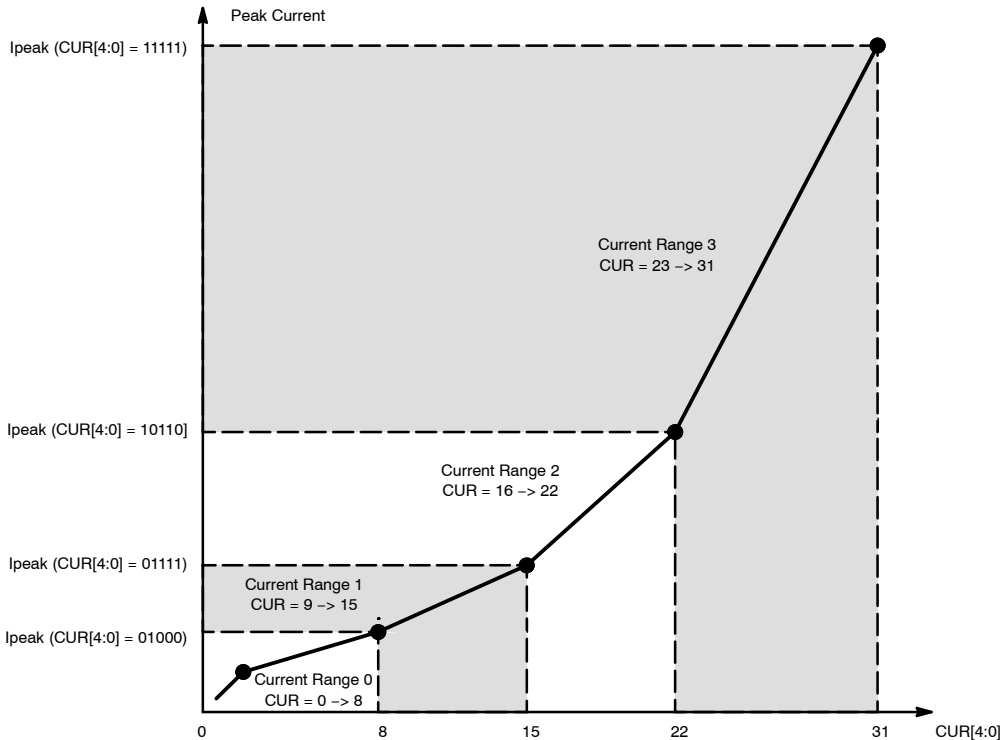


Figure 12. Programmable Peak-Current Overview

Speed and Load-Angle Output

The SLA-pin provides an output voltage that indicates the level of the Back-e.m.f. voltage of the motor. This Back-e.m.f. voltage is sampled during every so-called “coil

current zero crossings”. Per coil, 2 zero-current positions exist per electrical period, yielding in total 4 zero-current observation points per electrical period.

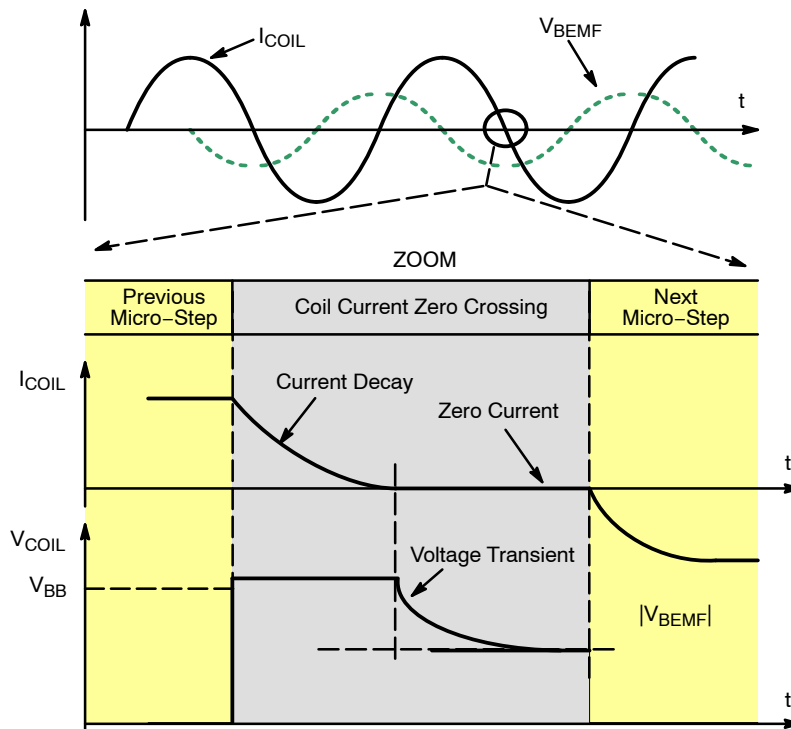


Figure 13. Principle of BEMF measurement

Because of the relatively high re-circulation currents in the coil during current decay, the coil voltage V_{COIL} shows a transient behavior. As this transient is not always desired in application software, two operating modes can be selected by means of the bit <SLAT> (see "SLA-transparency" in Table 12). The SLA pin shows in "transparent mode" full visibility of the voltage transient behavior. This allows a sanity-check of the speed-setting versus motor operation and characteristics and supply voltage levels. If the bit "SLAT" is cleared, then only the voltage samples at the end of each coil current zero crossing are visible on the

SLA-pin. Because the transient behavior of the coil voltage is not visible anymore, this mode generates smoother Back e.m.f. input for post-processing, e.g. by software.

In order to bring the sampled Back e.m.f. to a descent output level (0 V to 5 V), the sampled coil voltage V_{COIL} is divided by 2 or by 4. This divider is set through a SPI bit <SLAG>. (See Table 12)

The following drawing illustrates the operation of the SLA-pin and the transparency-bit. "PWMsh" and " $I_{COIL} = 0$ " are internal signals that define together with SLAT the sampling and hold moments of the coil voltage.

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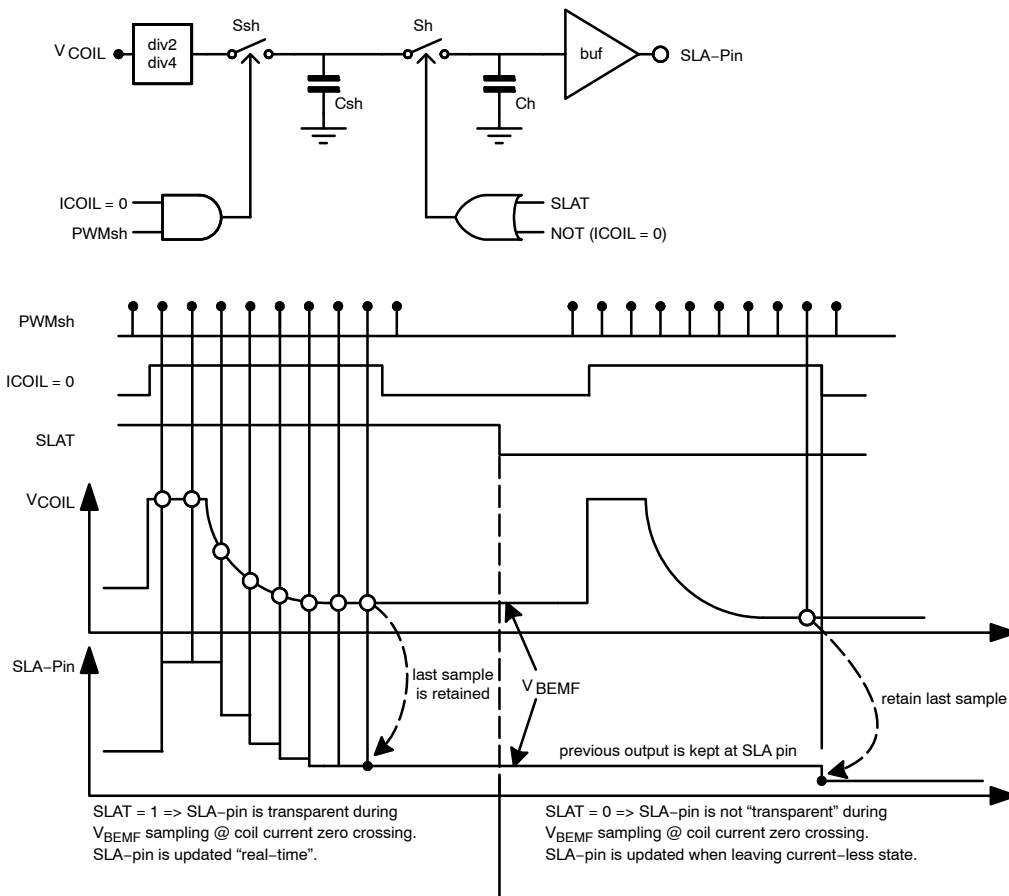


Figure 14. Timing Diagram of SLA-Pin

Warning, Error Detection and Diagnostics Feedback

Thermal Warning and Shutdown

When Junction temperature rises above T_{TW} , the thermal warning bit <TW> is set (Table 15 SPI Status Register 0). If junction temperature increases above thermal shutdown level, then the circuit goes in "Thermal Shutdown" mode (<TSD>) and all driver transistors are disabled (high impedance) (Table 15 SPI Status Register 2). The conditions to reset flag <TSD> is to be at a temperature lower than T_{TW} and to clear the <TSD> flag by reading it using any SPI read command.

Overcurrent Detection

The overcurrent detection circuit monitors the load current in each activated output stage. If the load current exceeds the overcurrent detection threshold, then the overcurrent flag is set and the drivers are switched off to reduce the power dissipation and to protect the integrated circuit. Each driver transistor has an individual detection bit in the Table 15 SPI status registers 1 and SPI Status Register 2 (<OVXij> and <OVYij>). Error condition is latched and the microcontroller needs to clear the status bits to reactivate the drivers.

Note: Successive reading the SPI Status Registers 1 and 2 in case of a short circuit condition, may lead to damage to the drivers.

Open Coil/Current Not Reached Detection

Open coil detection is based on the observation of 100% duty cycle of the PWM regulator. If in a coil 100% duty cycle is detected for longer than 32 ms the appropriate status bit in the SPI status register is set (<OPENX> or <OPENY>). (Table 15: SPI Status Register 0)

When the resistance of a motor coil is very large and the battery voltage is low, it can happen that the motor driver is not able to deliver the requested current to the motor. Under these conditions the PWM controller duty cycle will be 100% and after 32 ms, the error pin and <OPENX>, <OPENY> will flag this situation (motor current is kept alive). This feature can be used to test if the operating conditions (supply voltage, motor coil resistance) still allow reaching the requested coil-current or else the coil-current should be reduced.

Charge Pump Failure

The charge pump is an important circuit that guarantees low $R_{DS(on)}$ for all drivers, especially for low supply voltages. If the supply voltage is too low or external components are not properly connected to guarantee $R_{DS(on)}$ of the drivers, then the bit <CPFAIL> is set in the SPI status register 0. Also after power-on-reset the charge pump voltage will need some time to exceed the required threshold. During that time <CPFAIL> will be set to “1”.

Error Output

This is an open drain digital output to flag a problem to the external microcontroller. The signal on this output is active low and the logic combination of:

$\text{NOT}(\overline{\text{ERR}}) = \text{<TW> OR <TSD> OR <OVXij> OR <OVYij> OR <OPENi> OR <CPFAIL>}$

CLR Pin (=Hard Reset)

Logic 0 on CLR pin allows normal operation of the chip. To reset the complete digital inside the AMIS–30521/NCV70521, the input CLR needs to be pulled to logic 1 during minimum time given by t_{CLR} . (See AC Parameters) This reset function clears all internal registers without the need of a power-cycle except in sleep mode. The operation of all analog circuits is depending on the reset state of the

digital, charge pump remains active. Logic 0 on CLR pin resumes normal operation again.

Sleep Mode

The bit <SLP> in SPI control register 2 is provided to enter a so-called “sleep mode”. This mode allows reduction of current-consumption when the motor is not in operation. The effect of sleep mode is as follows:

- The Drivers are Put in HiZ
- All Analog Circuits are Disabled and in Low-Power Mode
- All Internal Registers are Maintaining Their Logic Content
- NXT and DIR Inputs are Ignored
- SPI Communication Remains Possible (Slight Current Increase During SPI Communication)
- Oscillator and Digital Clocks are Silent, Except During SPI Communication

Normal operation is resumed after writing logic '0' to bit <SLP>. A startup time is needed for the charge pump to stabilize. After this time, NXT commands can be issued. When the device is in sleep mode and V_{BB} becomes lower than V_{BB_min} the device might reset.

SPI INTERFACE

The serial peripheral interface (SPI) allows an external microcontroller (Master) to communicate with the AMIS–30521/NCV70521. The implemented SPI block is designed to interface directly with numerous microcontrollers from several manufacturers. The AMIS–30521/NCV70521 acts always as a Slave and cannot initiate any transmission. The operation of the device is configured and controlled by means of SPI registers which are observable for read and/or write from the Master.

SPI Transfer Format and Pin Signals

During a SPI transfer, data is simultaneously transmitted (shifted out serially) and received (shifted in serially). A serial clock line (CLK) synchronizes shifting and sampling of the information on the two serial data lines (DO and DI).

DO signal is the output from the Slave (AMIS–30521/NCV70521), and DI signal is the output from the Master. A chip select line (\overline{CS}) allows individual selection of a Slave SPI device in a multiple-slave system. The \overline{CS} line is active low. If the AMIS–30521/NCV70521 is not selected, DO is pulled up with the external pull up resistor. Since AMIS–30521/NCV70521 operates as a Slave in MODE 0 (CPOL = 0; CPHA = 0) it always clocks data out on the falling edge and samples data in on rising edge of clock. The Master SPI port must be configured in MODE 0 too, to match this operation. The SPI clock idles low between the transferred bytes.

The diagram below is both a Master and a Slave timing diagram since CLK, DO and DI pins are directly connected between the Master and the Slave.

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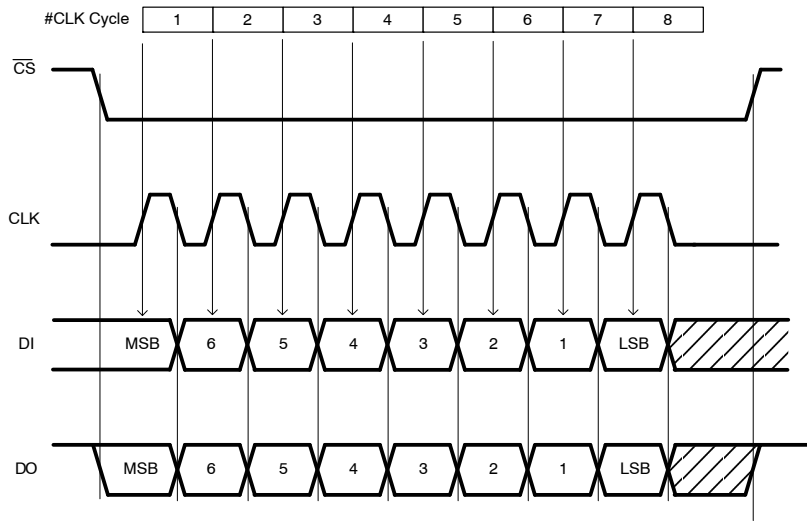


Figure 15. Timing Diagram of a SPI Transfer

NOTE: At the falling edge of the eighth clock pulse the data-out shift register is updated with the content of the addressed internal SPI register. The internal SPI registers are updated at the first rising edge of the AMIS-30521/NCV70521 system clock when \overline{CS} = High.

Transfer Packet

Serial data transfer is assumed to follow MSB first rule. The transfer packet contains one or more bytes.

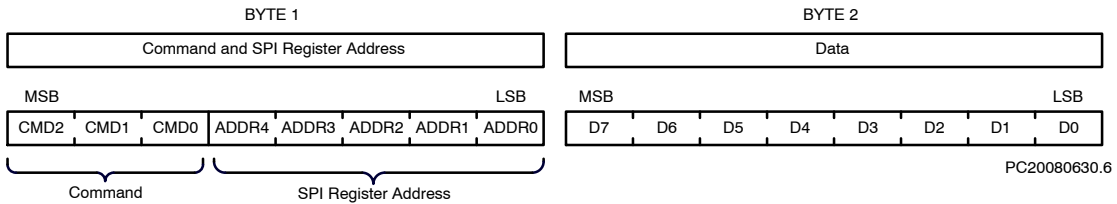


Figure 16. SPI Transfer Packet

Byte 1 contains the Command and the SPI Register Address and indicates to the AMIS-30521/NCV70521 the chosen type of operation and addressed register. Byte 2 contains data, or sent from the Master in a WRITE operation, or received from the AMIS-30521/NCV70521 in a READ operation.

Two command types can be distinguished in the communication between Master and AMIS-30521/NCV70521:

- READ from SPI Register with address ADDR[4:0]:
CMD[2:0] = "000"
- WRITE to SPI Register with address ADDR[4:0]:
CMD[2:0] = "100"

READ Operation

If the Master wants to read data from Status or Control Registers, it initiates the communication by sending a READ command. This READ command contains the address of the SPI register to be read out. At the falling edge of the eighth clock pulse the data-out shift register is updated with the content of the corresponding internal SPI register. In the next 8-bit clock pulse train this data is shifted out via DO pin. At the same time the data shifted in from DI (Master) should be interpreted as the following successive command or the same command.

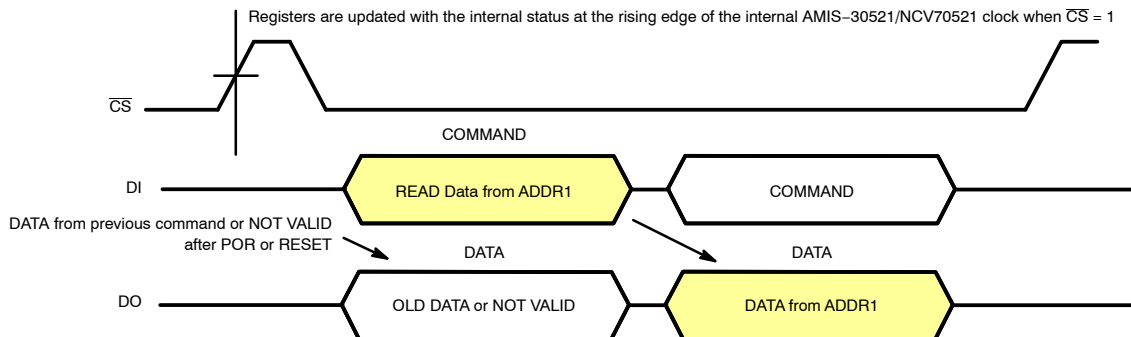


Figure 17. Single READ Operation where DATA from SPI Register with Address 1 is Read by the Master

All 4 Status Registers (see SPI Registers) contain 7 data bits and an even parity check bit. The most significant bit (D7) represents a parity of D[6:0]. If the number of logical ones in D[6:0] is odd, the parity bit D7 equals “1”. If the number of logical ones in D[6:0] is even then the parity bit D7 equals “0”. This simple mechanism protects against noise and increases the consistency of the transmitted data. If a parity check error occurs it is recommended to initiate an additional READ command to obtain the status again.

Also the Control Registers can be read out following the same routine. Control Registers don’t have a parity check.

The \overline{CS} line is active low and may remain low between successive READ commands as illustrated in Figure 19. There is however one exception. In case an error condition is latched in one of Status Registers (see SPI Registers) the \overline{ERR} pin is activated. (See the “Error Output” Section). This signal flags a problem to the external microcontroller. By reading the Status Registers information, the root cause of the problem can be determined. After this READ operation the Status Registers are cleared. Because the Status Registers and \overline{ERR} pin (see SPI Registers) are only updated by the internal system clock when the \overline{CS} line is high, the Master should force \overline{CS} high immediately after the READ

operation. For the same reason it is recommended to keep the \overline{CS} line high always when the SPI bus is idle.

WRITE Operation

If the Master wants to write data to a Control Register it initiates the communication by sending a WRITE command. This contains the address of the SPI register to write to. The command is followed with a data byte. This incoming data will be stored in the corresponding Control Register after \overline{CS} goes from low to high! AMIS-30521/NCV70521 responds on every incoming byte by shifting out via DO the data stored in the last received address.

It is important that the writing action (command – address and data) to the Control Register is exactly 16 bits long. If more or less bits are transmitted the complete transfer packet is ignored.

A WRITE command executed for a read-only register (e.g. Status Registers) will not affect the addressed register and the device operation.

Because after a power-on-reset the initial address is unknown the data shifted out via DO is not valid.

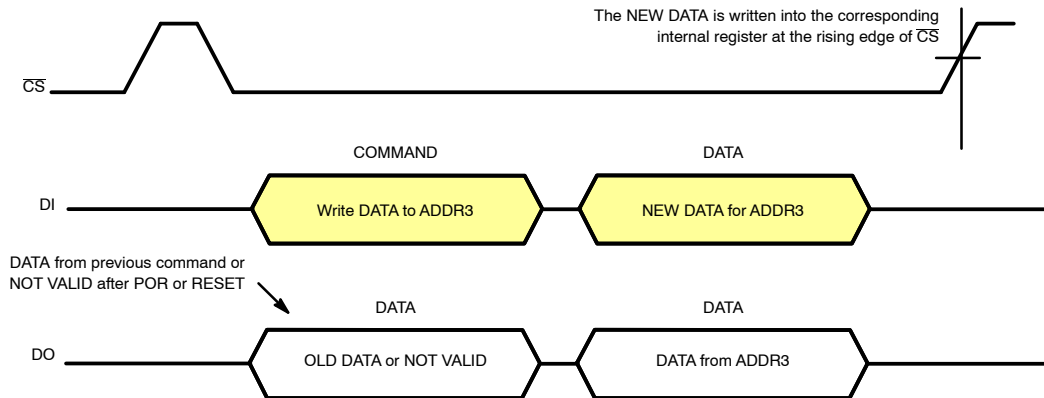


Figure 18. Single WRITE Operation Where DATA from the Master is Written in SPI Register with Address 3

Examples of Combined READ and WRITE Operations

In the following examples successive READ and WRITE operations are combined. In Figure 19 the Master first reads the status from Register at ADDR4 and at ADDR5 followed

by writing a control byte in Control Register at ADDR2. Note that during the write command (in Figures 18 and 19) the old data of the pointed register is returned at the moment the new data is shifted in.

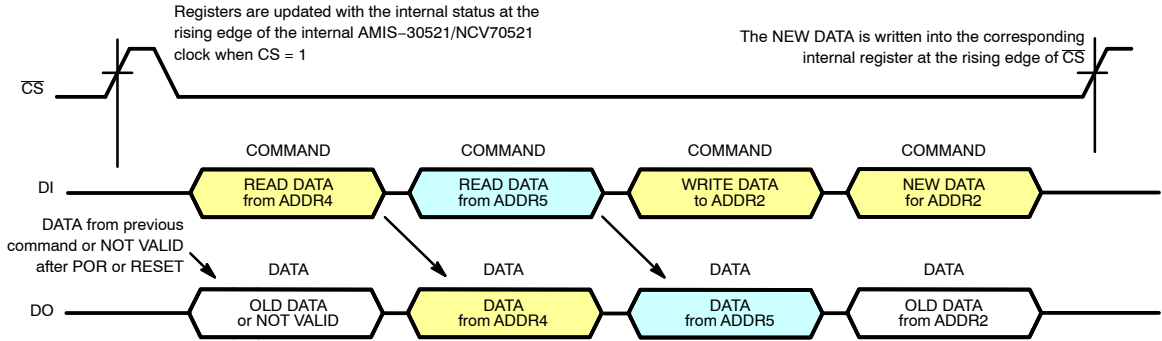


Figure 19. Two Successive READ Commands Followed by a WRITE Command

After the write operation the Master could initiate a read back command in order to verify if the data is correctly written, as illustrated in Figure 20. During reception of the READ command the old data is returned for a second time. Only after receiving the READ command the new data is

transmitted. This rule also applies when the master device wants to initiate an SPI transfer to read the Status Registers. Because the internal system clock updates the Status Registers only when CS line is high, the first read out byte might represent old status information.

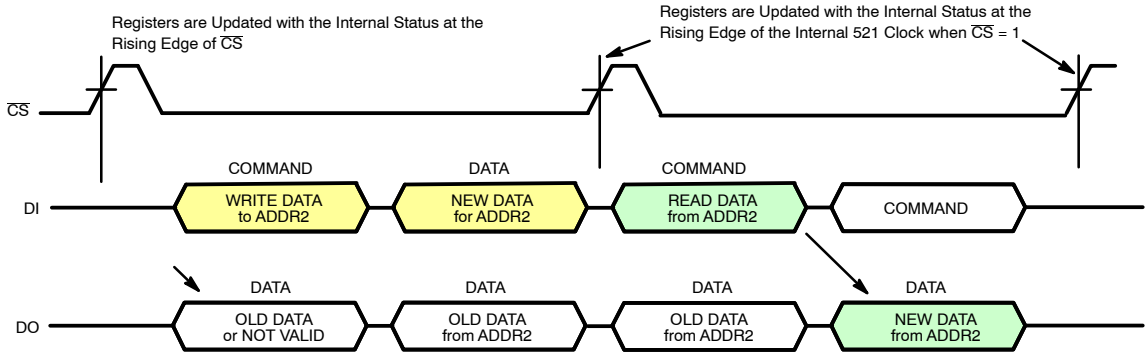


Figure 20. A WRITE Operation Where DATA From the Master is Written in SPI Register with Address 2 Followed by a READ Back Operation to Verify a Correct WRITE Operation

NOTE: The internal data-out shift buffer of the AMIS-30521/NCV70521 is updated with the content of the selected SPI register only at the last (every eighth) falling edge of the CLK signal (see SPI Transfer Format and Pin Signals). As a result, new data for transmission cannot be written to the shift buffer at the beginning of the transfer packet and the first byte shifted out might represent old data.

Table 11. SPI CONTROL REGISTERS (All SPI Control Registers have Read/Write Access and default to "0" after Power-on or hard reset)

| Address | Content | Structure | | | | | | | |
|-----------|---------|-----------|-------|-------|-------|-------|----------|----------|-------|
| | | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 |
| | | Access | R/W | R/W | R/W | R/W | R/W | R/W | R/W |
| CR0 (01h) | Data | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| CR1 (02h) | Data | SM[2:0] | | | | | CUR[4:0] | | |
| CR2 (03h) | Data | DIRCTRL | NXTP | - | - | PWMF | PWMJ | EMC[1:0] | |
| | | MOTEN | SLP | SLAG | SLAT | - | - | - | - |

Where:

R/W: Read and Write access

Reset: Status after Power-On or hard reset

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Table 12. SPI CONTROL PARAMETER OVERVIEW

| Symbol | Description | Status | | Value |
|----------|---|-------------|-------------------------|------------|
| DIRCTRL | Controls the Direction of Rotation (in Combination with Logic Level on Input DIR) | <DIR> = 0 | <DIRCTRL> = 0 | CW Motion |
| | | | <DIRCTRL> = 1 | CCW Motion |
| | | <DIR> = 1 | <DIRCTRL> = 0 | CCW Motion |
| | | | <DIRCTRL> = 1 | CW Motion |
| EMC[1:0] | Turn On- and Turn-off Slopes (Note 15) | 00 | Very Fast | |
| | | 01 | Fast | |
| | | 10 | Slow | |
| | | 11 | Very Slow | |
| MOTEN | Activates the Motor Driver Outputs | <MOTEN> = 0 | Drivers Disabled | |
| | | <MOTEN> = 1 | Drivers Enabled | |
| NXTP | Selects if NXT triggers on Rising or Falling Edge | <NXTP> = 0 | Trigger on Rising Edge | |
| | | <NXTP> = 1 | Trigger on Falling Edge | |
| PWMF | Enables Doubling of the PWM Frequency (Note 15) | <PWMF> = 0 | Default Frequency | |
| | | <PWMF> = 1 | Double Frequency | |
| PWMJ | Enables Jitter PWM | <PWMJ> = 0 | Jitter Disabled | |
| | | <PWMJ> = 1 | Jitter Enabled | |
| SM[2:0] | Stepmode | 000 | 1/32 | Micro Step |
| | | 001 | 1/16 | Micro Step |
| | | 010 | 1/8 | Micro Step |
| | | 011 | 1/4 | Micro Step |
| | | 100 | Compensated Half Step | |
| | | 101 | Uncompensated half Step | |
| | | 110 | Full Step | |
| | | 111 | n.a. | |
| SLAG | Speed Load Angle Gain Setting | <SLAG> = 0 | Gain = 0.5 | |
| | | <SLAG> = 1 | Gain = 0.25 | |
| SLAT | Speed Load Angle Transparency Bit | <SLAT> = 0 | SLA is NOT Transparent | |
| | | <SLAT> = 1 | SLA is Transparent | |
| SLP | Enables Sleep Mode | <SLP> = 0 | Active Mode | |
| | | <SLP> = 1 | Sleep Mode | |

15. The typical values can be found in Table 5: DC Parameters and Table 6: AC Parameters

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CUR[4:0] Selects IMCmax peak. This is the peak or amplitude of the regulated current waveform in the motor coils.

Table 13. SPI CONTROL PARAMETER OVERVIEW: CURRENT AMPLITUDE CUR[4:0]

| Current Range (Note 17) | Index CUR[4:0] | Current (mA) (Note 16) | Current Range (Note 17) | Index CUR[4:0] | Current (mA) (Note 16) |
|----------------------------|-------------------|---------------------------|----------------------------|-------------------|---------------------------|
| 0 | 0 00000 | 33 | 2 | 16 10000 | 365 |
| | 1 00001 | 64 | | 17 10001 | 400 |
| | 2 00010 | 95 | | 18 10010 | 440 |
| | 3 00011 | 104 | | 19 10011 | 485 |
| | 4 00100 | 115 | | 20 10100 | 530 |
| | 5 00101 | 126 | | 21 10101 | 585 |
| | 6 00110 | 138 | | 22 10110 | 630 |
| | 7 00111 | 153 | | 3 | 23 10111 |
| 8 01000 | 166 | 24 11000 | 825 | | |
| 9 01001 | 190 | 25 11001 | 895 | | |
| 10 01010 | 205 | 26 11010 | 975 | | |
| 11 01011 | 230 | 27 11011 | 1065 | | |
| 12 01100 | 250 | 28 11100 | 1155 | | |
| 13 01101 | 275 | 29 11101 | 1245 | | |
| 14 01110 | 300 | 30 11110 | 1365 | | |
| 15 01111 | 325 | 31 11111 | 1480 | | |

16. Typical current amplitude at $T_J = 125$.

17. Reducing the current over different current ranges might trigger overcurrent detection, please refer to dedicated application note for solutions.

SPI Status Register Description

All 4 SPI Status Registers have Read Access and are default to "0" after Power-on or hard reset.

Table 14. SPI STATUS REGISTERS

| Address | Content | Structure | | | | | | | |
|---------|------------------|-----------|----------|--------|---------|--------|-------|-------|-------|
| | | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 |
| | | Access | R | R | R | R | R | R | R |
| | Reset | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| SR0 04h | Data Not Latched | PAR | TW | CPfail | - | OPENX | OPENY | - | - |
| SR1 05h | Data is Latched | PAR | OVCXPT | OVCXPB | OVCXNT | OVCXNB | - | - | - |
| SR2 06h | Data is Latched | PAR | OVCYPT | OVCYPB | OVCYYNT | OVCYNB | TSD | - | - |
| SR3 07h | Data Not Latched | PAR | MSP[6:0] | | | | | | |

Where:

R Read only mode access
 Reset Status after Power-On or hard reset
 PAR Parity check

Table 15. SPI STATUS FLAGS OVERVIEW

| Mnemonic | Flag | Length (bit) | Related SPI Register | Comment | Reset State |
|----------|---|--------------|----------------------|--|-------------|
| CPFail | Charge Pump Failure | 1 | Status Register 0 | '0' = no failure '1' = failure: indicates that the charge pump does not reach the required voltage level. | '0' |
| MSP[6:0] | Micro Step Position | 7 | Status Register 3 | Translator micro step position | '0000000' |
| OPENX | OPEN Coil X | 1 | Status Register 0 | '1' = Open coil detected | '0' |
| OPENY | OPEN Coil Y | 1 | Status Register 0 | '1' = Open coil detected | '0' |
| OVCXNB | Overcurrent at MOTXN Terminal; Bottom Transistor | 1 | Status Register 1 | '0' = no failure '1' = failure: indicates that over current is detected at bottom transistor XN-terminal | '0' |
| OVCXNT | Overcurrent at MOTXN Terminal; Top Transistor | 1 | Status Register 1 | '0' = no failure '1' = failure: indicates that over current is detected at top transistor XN-terminal | '0' |
| OVCXPB | Overcurrent at MOTXP Terminal; Bottom Transistor | 1 | Status Register 1 | '0' = no failure '1' = failure: indicates that overcurrent is detected at bottom transistor XP-terminal | '0' |
| OVCXPT | Overcurrent at MOTXP Terminal; Top Transistor | 1 | Status Register 1 | '0' = no failure '1' = failure: indicates that overcurrent is detected at top transistor XP-terminal | '0' |
| OVCYNB | Overcurrent at MOTYN Terminal; Bottom Transistor | 1 | Status Register 2 | '0' = no failure '1' = failure: indicates that overcurrent is detected at bottom transistor YN-terminal | '0' |
| OVCYNT | Overcurrent at MOTYN Terminal; Top Transistor | 1 | Status Register 2 | '0' = no failure '1' = failure: indicates that overcurrent is detected at top transistor YN-terminal | '0' |
| OVCYPB | Overcurrent at MOTYP Terminal; Bottom Transistor. | 1 | Status Register 2 | '0' = no failure '1' = failure: indicates that overcurrent is detected at bottom transistor YP-terminal | '0' |
| OVCYPT | Overcurrent at MOTYP Terminal; Top Transistor. | 1 | Status Register 2 | '0' = no failure '1' = failure: indicates that overcurrent is detected at top transistor YP-terminal | '0' |
| TSD | Thermal Shutdown | 1 | Status Register 2 | | '0' |
| TW | Thermal Warning | 1 | Status Register 0 | | '0' |

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DEVICE ORDERING INFORMATION

| Part Number | Temperature Range | Package Type | Peak Current | Shipping [†] |
|-------------------|-------------------|----------------------|--------------|-----------------------|
| AMIS30521C5212RG | -40°C - 125°C | NQFP-32 (Pb-Free) | 1600 mA | Tape & Reel |
| AMIS30521C5212G | -40°C - 125°C | NQFP-32 (Pb-Free) | 1600 mA | Tube / Tray |
| NCV70521MN003R2G* | -40°C - 125°C | NQFP-32 (Pb-Free) | 1600 mA | Tape & Reel |
| NCV70521MN003G* | -40°C - 125°C | NQFP-32 (Pb-Free) | 1600 mA | Tube / Tray |

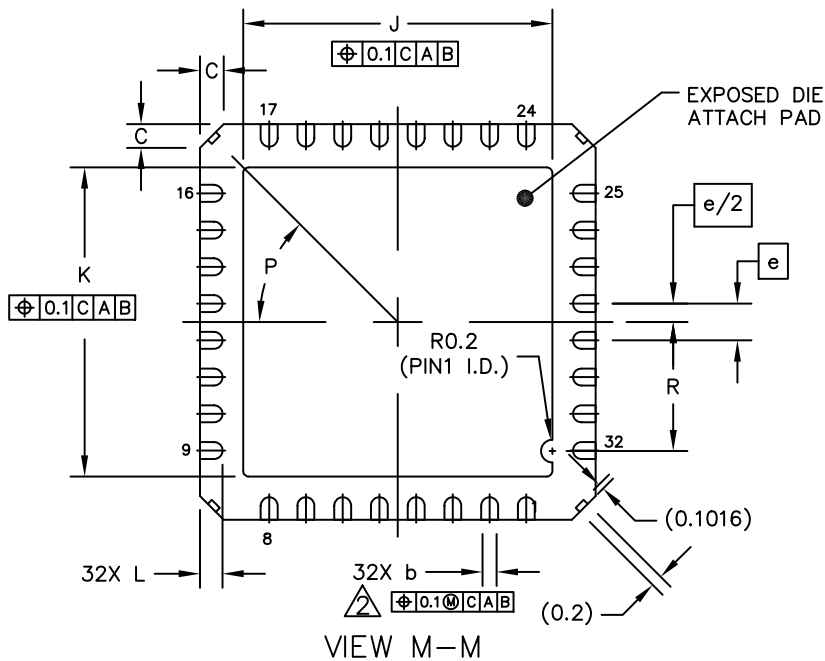
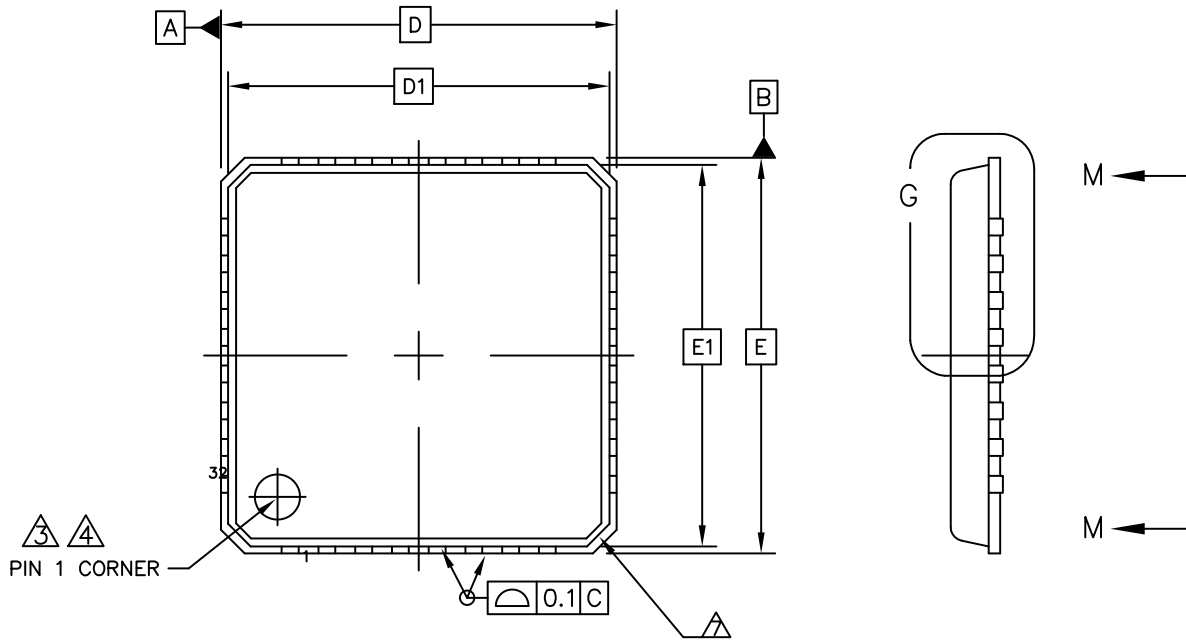
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*Qualified for automotive applications.

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

QFN32, 7x7
CASE 560AA
ISSUE A

DATE 23 SEP 2015

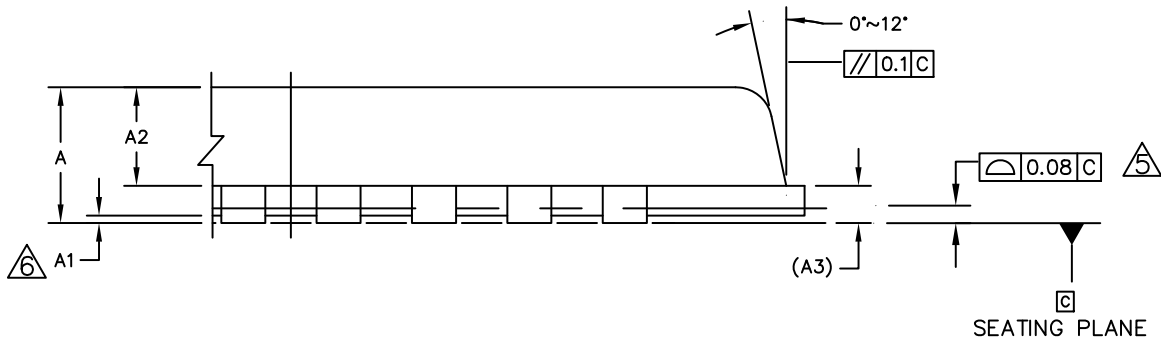


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QFN32, 7x7
CASE 560AA
ISSUE A

DATE 23 SEP 2015



DETAIL G
VIEW ROTATED 90° CLOCKWISE

| DIM | MIN | NOM | MAX | NOTES |
|-----|-------|------------|--------------------------|---|
| A | 0.8 | | 0.9 | 1. DIE THICKNESS ALLOWABLE IS 0.305mm MAXIMUM (.012 INCHES MAXIMUM) ⚠ DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.2 AND 0.25mm FROM TERMINAL TIP. ⚠ THE PIN #1 IDENTIFIER MUST BE PLACED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY. ⚠ EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL. ⚠ APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING. ⚠ APPLIED ONLY TO TERMINALS. ⚠ EXACT SHAPE OF EACH CORNER IS OPTIONAL. |
| A1 | 0 | 0.02 | 0.05 | |
| A2 | 0.576 | 0.615 | 0.654 | |
| A3 | | 0.203 REF. | | |
| b | 0.25 | 0.3 | 0.35 | |
| C | 0.24 | 0.42 | 0.6 | |
| D | | 7 BSC | | |
| D1 | | 6.75 BSC | | |
| E | | 7 BSC | | |
| E1 | | 6.75 BSC | | |
| e | | 0.65 BSC | | |
| J | 5.37 | 5.47 | 5.57 | |
| K | 5.37 | 5.47 | 5.57 | |
| L | 0.35 | 0.4 | 0.45 | |
| P | | 45° REF | | |
| R | 2.185 | | 2.385 | |
| | | UNIT | DIMENSION AND TOLERANCES | |
| | | MM | ASME_Y14.5M | JEDEC-MO-220-REV.F |

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